

STP80NF70

N-channel 68 V, 0.0082 Ω 98 A, TO-220 STripFET™ II Power MOSFET

Features

Туре	V _{DSS}	R _{DS(on)} max	I _D
STP80NF70	68 V	< 0.0098 Ω	98 A

- Exceptional dv/dt capability
- 100% avalanche tested

Application

■ Switching applications

Description

The STP80NF70 is a N-channel Power MOSFET realized with STMicroelectronics unique STripFET™ process. It has specifically been designed to minimize input capacitance and gate charge. The device is therefore suitable in advanced high-efficiency switching applications.

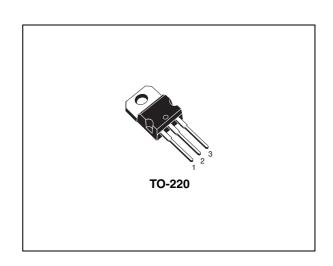


Figure 1. Internal schematic diagram

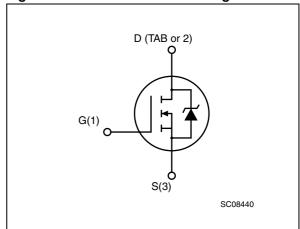


Table 1. Device summary

Order code	Marking	Package	Packaging
STP80NF70	80NF70	TO-220	Tube

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STP80NF70 Electrical ratings

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source voltage (V _{GS} = 0)	68	V
V _{GS}	Gate-source voltage	± 20	V
I _D	Drain current (continuous) at T _C = 25 °C	98	Α
I _D	Drain current (continuous) at T _C =100 °C	68	Α
I _{DM} ⁽¹⁾	Drain current (pulsed)	392	Α
P _{TOT}	Total dissipation at T _C = 25 °C	190	W
	Derating factor	1.27	W/°C
dv/dt (2)	Peak diode recovery voltage slope	13	V/ns
E _{AS} (3)	Single pulse avalanche energy	700	mJ
T _{stg}	Storage temperature		°C
T _J	Operating junction temperature	-55 to 175	

^{1.} Pulse width limited by safe operating area.

Table 3. Thermal data

Symbol	Parameter	Value	Unit
R _{thj-case}	Thermal resistance junction-case max	0.79	°C/W
R _{thj-amb}	Thermal resistance junction-ambient max	62.5	°C/W
T _I	Maximum lead temperature for soldering purpose ⁽¹⁾	300	°C

^{1. 1.6} mm from case for 10 sec.

^{2.} $I_{SD} \le 80$ A, di/dt ≤ 300 A/ μ s, $V_{DD} \le V_{(BR)DSS}$, $T_{J} \le T_{JMAX}$.

^{3.} Starting $T_J = 25$ °C, $I_D = 40$ A, $V_{DD} = 34$ V.

Electrical characteristics STP80NF70

2 Electrical characteristics

(T_{CASE}=25°C unless otherwise specified).

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	$I_D = 250 \mu\text{A}, V_{GS} = 0$	68			٧
I _{DSS}	Zero gate voltage drain current (V _{GS} = 0)	V_{DS} = Max rating, V_{DS} = Max rating @125 °C			1 10	μ Α μ Α
I _{GSS}	Gate body leakage current (V _{DS} = 0)	V _{GS} = ±20 V			±100	nA
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2	3	4	٧
R _{DS(on)}	Static drain-source on resistance	V _{GS} = 10 V, I _D = 40 A		0.0082	0.0098	Ω

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
g _{fs} ⁽¹⁾	Forward transconductance	$V_{DS} = 15 \text{ V}, I_{D} = 40 \text{ A}$	-	60	-	S
C _{iss} C _{oss} C _{rss}	Input capacitance Output capacitance Reverse transfer capacitance	V _{DS} =25 V, f = 1 MHz, V _{GS} = 0	-	2550 550 175	-	pF pF pF
Q _g Q _{gs} Q _{gd}	Total gate charge Gate-source charge Gate-drain charge	$V_{DD} = 34 \text{ V}, I_{D} = 80 \text{ A}$ $V_{GS} = 10 \text{ V}$	-	75 17 30	1	nC nC nC

^{1.} Pulsed: pulse duration=300 μ s, duty cycle 1.5%.

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
$t_{\rm d(on)} \\ t_{\rm r} \\ t_{\rm d(off)} \\ t_{\rm f}$	Turn-on delay time Rise time Turn-off delay time Fall time	V_{DD} = 34 V, I_{D} = 40 A, R_{G} =4.7 Ω , V_{GS} =10 V Figure 13 on page 9	1	17 60 90 75	-	ns ns ns ns

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{SD}	Source-drain current		-		98	Α
I _{SDM} ⁽¹⁾	Source-drain current (pulsed)		-		392	Α
V _{SD} ⁽²⁾	Forward on voltage	$I_{SD} = 80 \text{ A}, V_{GS} = 0$	-		1.5	V
t _{rr} Q _{rr} I _{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD} = 80 \text{ A},$ di/dt = 100 A/ μ s, $V_{DD} = 25 \text{ V}, T_{J} = 150 ^{\circ}\text{C}$ Figure 15 on page 9	-	70 160 4.7		ns nC A

^{1.} Pulse width limited by safe operating area.

^{2.} Pulsed: pulse duration=300µs, duty cycle 1.5%

Electrical characteristics STP80NF70

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

Figure 3. Thermal impedance

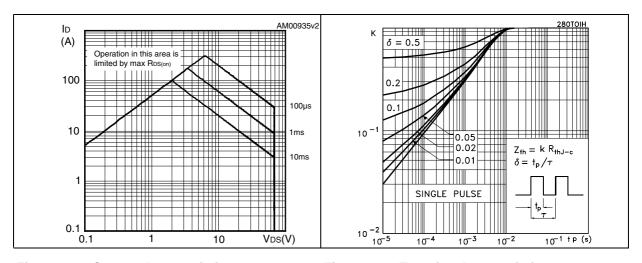
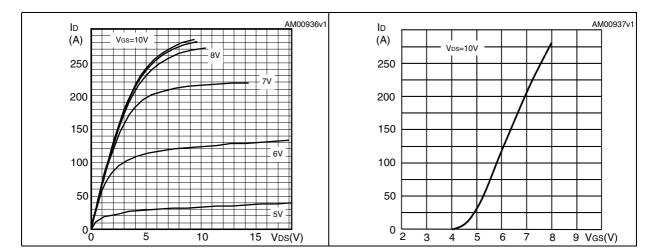


Figure 4. Output characteristics

Figure 5. Transfer characteristics



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Figure 6. Normalized BV_{DSS} vs temperature Figure 7. Static drain-source on resistance

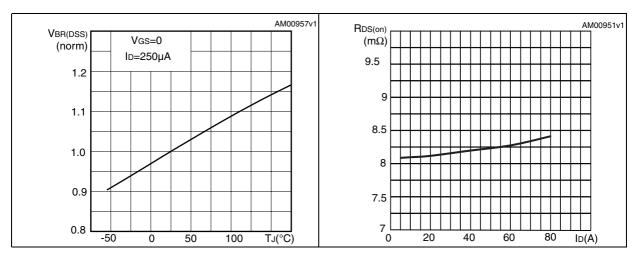


Figure 8. Gate charge vs gate-source voltage Figure 9. Capacitance variations

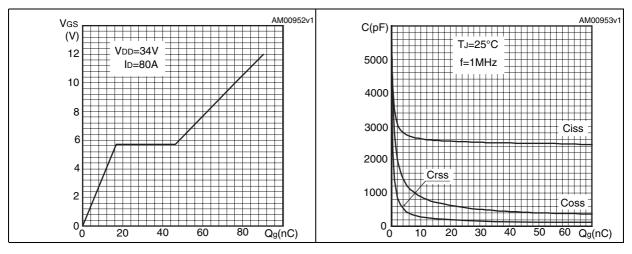
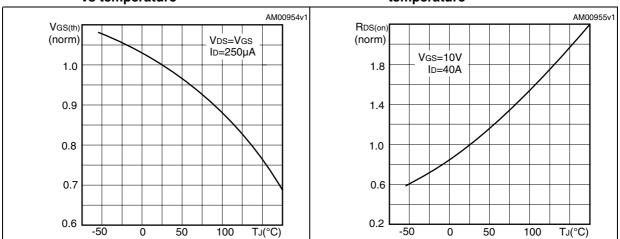
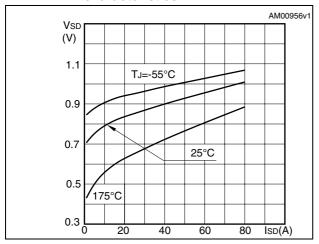


Figure 10. Normalized gate threshold voltage Figure 11. Normalized on resistance vs vs temperature temperature



Electrical characteristics STP80NF70

Figure 12. Source-drain diode forward characteristics



STP80NF70 Test circuits

3 Test circuits

Figure 13. Switching times test circuit for resistive load

Figure 14. Gate charge test circuit

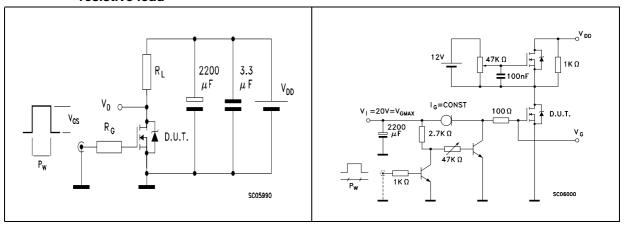


Figure 15. Test circuit for inductive load switching and diode recovery times

Figure 16. Unclamped inductive load test circuit

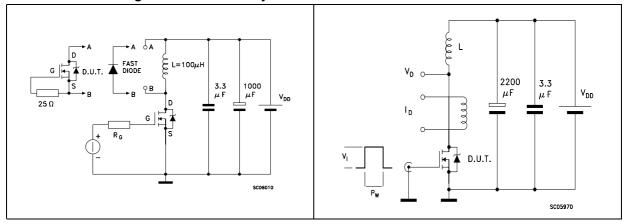
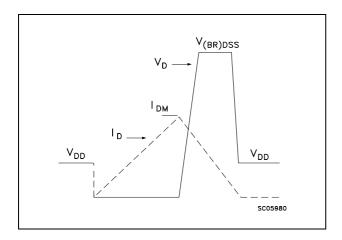


Figure 17. Unclamped inductive waveform



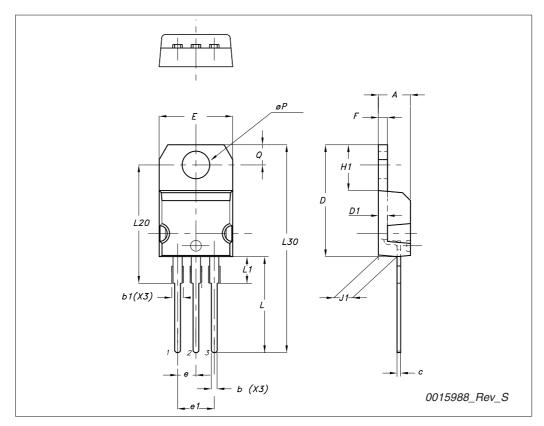
4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

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TO-220 type A mechanical data

Di		mm	
Dim	Min	Тур	Max
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
С	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
е	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
ØP	3.75		3.85
Q	2.65		2.95



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Revision history STP80NF70

5 Revision history

Table 8. Document revision history

Date	Revision	Changes
11-Jun-2010	1	First release.

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